

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0432028811

Status:

Active

Overview:

modular_plugs_jacks

Description:

Modular Jack, Right Angle, Low Profile, Shielded, All Panel Grounding Tabs, without Bottom Grounding Tab, Rear Position PCB Ground Tab, 8/10

Documents:

3D Model

Drawing (PDF)

Product Specification PS-43202-001 (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification

CSA

LR19980

UL

E107635

General

Product Family

Modular Jacks/Plugs

Series

43202

Component Type

PCB Jack

Magnetic

No

Overview

modular_plugs_jacks

Performance Category

3

Power over Ethernet (PoE)

N/A

Product Name

RJ45

Physical

Color - Resin

Black

Durability (mating cycles max)

500

Flammability

94V-0

Inverted / Top Latch

No

Lightpipes/LEDs

None

Material - Metal

Brass, Phosphor Bronze

Material - Plating Mating

Gold

Material - Plating Termination

Tin

Material - Resin

High Temperature Thermoplastic

Orientation

Right Angle (Side Entry)

PCB Retention

Yes

PCB Thickness Recommended (in)

0.062 In

PCB Thickness Recommended (mm)

1.60 mm

Packaging Type

Tray

Pitch - Mating Interface (in)

0.050 In

Pitch - Mating Interface (mm)

1.27 mm

Plating min: Mating (µin)

50

Plating min: Mating (µm)

1.25

Plating min: Termination (µin)

100

Plating min: Termination (µm)

2.5

Ports

1

Positions / Loaded Contacts

8/10

Surface Mount Compatible (SMC)

Yes

Temperature Range - Operating

-40°C to +85°C

Termination Interface: Style

Through Hole

Wire/Cable Type

N/A

Electrical

Current - Maximum per Contact

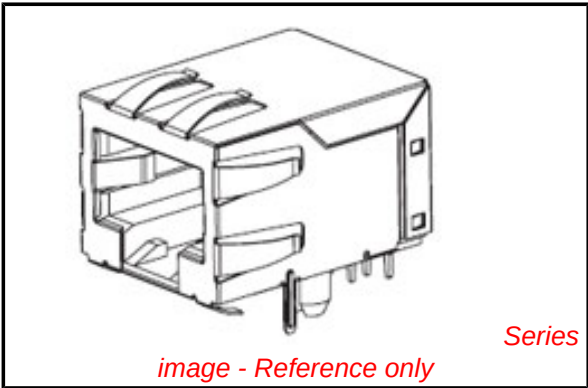
1.5A

Grounding to PCB

Yes

Grounding to Panel

Yes



EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Not Reviewed

Halogen-Free

Status

Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com

For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

43202Series

Mates With

FCC 68 Plugs

Shielded
Voltage - Maximum

Yes
125V

Solder Process Data

Lead-free Process Capability

Wave Capable (TH only)

Material Info

Reference - Drawing Numbers

Packaging Specification
Product Specification
Sales Drawing

PK-43202-004
PS-43202-001, RPS-43202-002
SDA-43202

This document was generated on 06/07/2010

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NOTES:

1) MATERIAL:

HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: SEE SHEETS 5 AND 6
INSULATOR: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: SEE SHEETS 5 AND 6
TERMINALS: PHOSPHOR BRONZE, .012/ 0.30 THICK
SHIELD: BRASS, .007/ 0.18 THICK

2) FINISH:

TERMINALS:

A = SELECT GOLD IN CONTACT AREA: 50 MICROINCHES / 1.27 MICROMETERS MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
B = SELECT GOLD IN CONTACT AREA: 30 MICROINCHES / 0.76 MICROMETERS MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS
DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD
IN THE PC TAILS AND/OR SHIELD.

SHIELD:

100 MICROINCHES / 2.54 MICROMETERS NICKEL OVER 50 MICROINCHES / 1.27
MICROMETERS COPPER UNDERPLATE PCB GROUND TABS DIPPED IN TIN

3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43202.

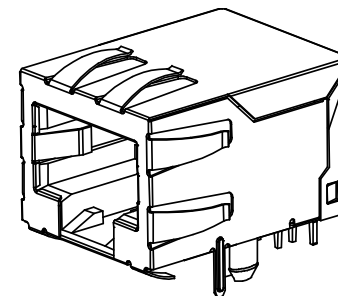
4) PACKAGING SPECIFICATION:

UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
PER MOLEX PACKAGING SPECIFICATION PK-43202-003.
UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN TUBES
PER MOLEX PACKAGING SPECIFICATION PK-43202-005.
SHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
PER MOLEX PACKAGING SPECIFICATION PK-43202-004.

5) SEE SHEETS 7 - 9 FOR P.C. BOARD LAYOUTS.

6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.

7) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.



SHIELDED MODULAR JACK
SHOWN WITH PANEL GROUND
OPTION 'D' AND FRONT
PCB GROUND TABS.

DRAWING LEGEND

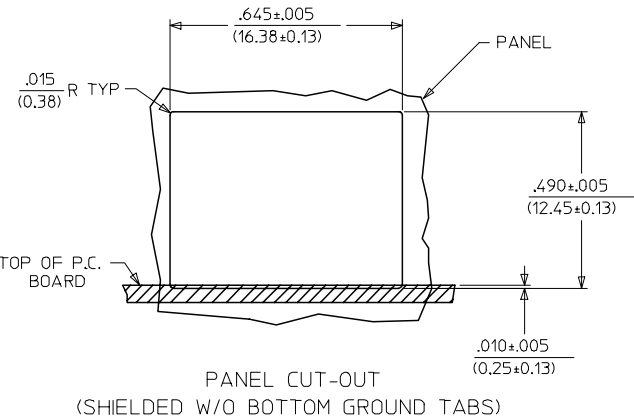
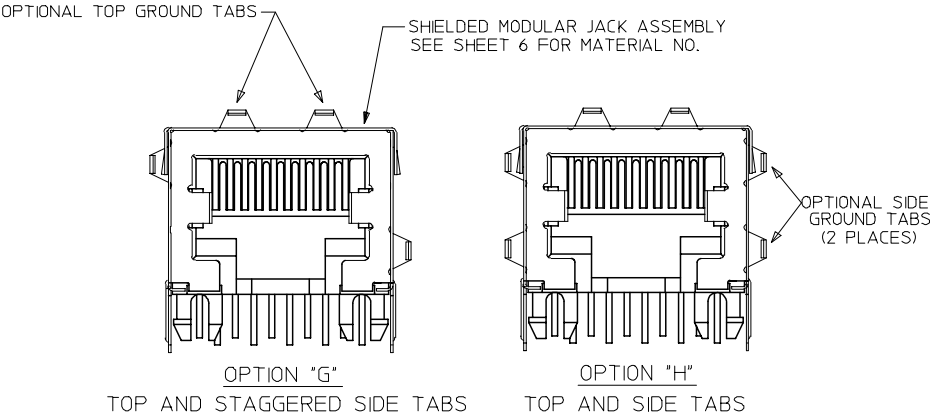
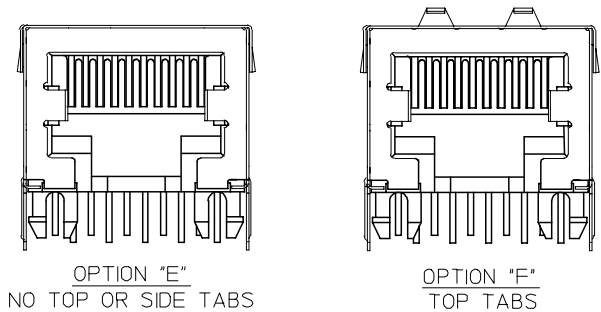
SHEET 1- NOTES, DRAWING LEGEND
SHEET 2- SHIELDED MODULAR JACK W/ BOTTOM GROUND TABS
SHEET 3- SHIELDED MODULAR JACK W/O BOTTOM GROUND TABS
SHEET 4- UNSHIELDED MODULAR JACK
SHEET 5- PART NUMBER CHARTS
SHEET 6- PART NUMBER CHARTS
SHEET 7- FOOTPRINT LAYOUT FOR 4 POSITION HOUSING
SHEET 8- FOOTPRINT LAYOUT FOR 6 POSITION HOUSING
SHEET 9- FOOTPRINT LAYOUT FOR 8 POSITION HOUSING

OBS COLORED JACKS EC NO: UCP2008-1189 DRAWN:JBELL 2007/11/30 CHKD:LSCHMIDT 2008/02/20 APPR:FSM/TH 2008/03/04	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY JTR	DATE 1993/03/31	TITLE ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY MOLEX INCORPORATED				
			4 PLACES	±.---	±.---	CHECKED BY JTR	DATE 1993/03/31					
			3 PLACES	±.---	±.010							
			2 PLACES	±.025	±.014	APPROVED BY RAS	DATE 1993/03/31					
			1 PLACE	±.036	±.---	ANGULAR ±1/2°		MATERIAL NO.		DOCUMENT NO.		SHEET NO.
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE SHTS 5&6		SDA-43202		1 OF 9		
						SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

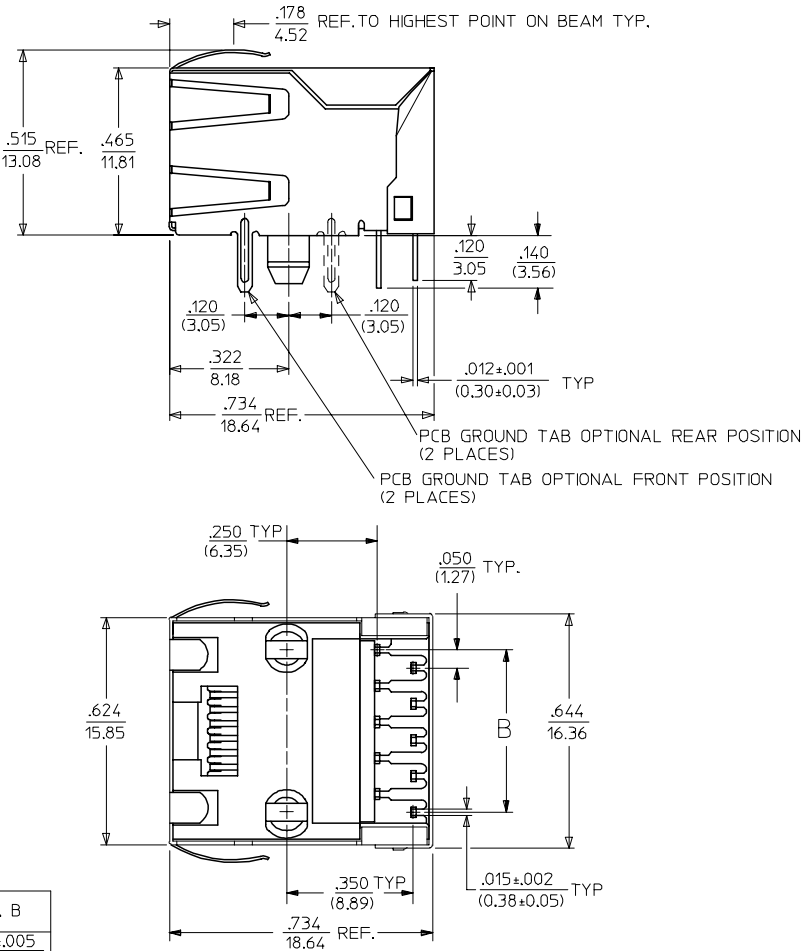
9	L2
8	L2
7	L2
6	L4
5	L
4	K2
3	L1
2	L1
1	L4
SH	REV

SHIELDED MODULAR JACK W/O BOTTOM GROUND TABS SIZE 8, LOADED 10 VERSION SHOWN

SIDE/TOP GROUND TAB OPTIONS FOR SHIELDS

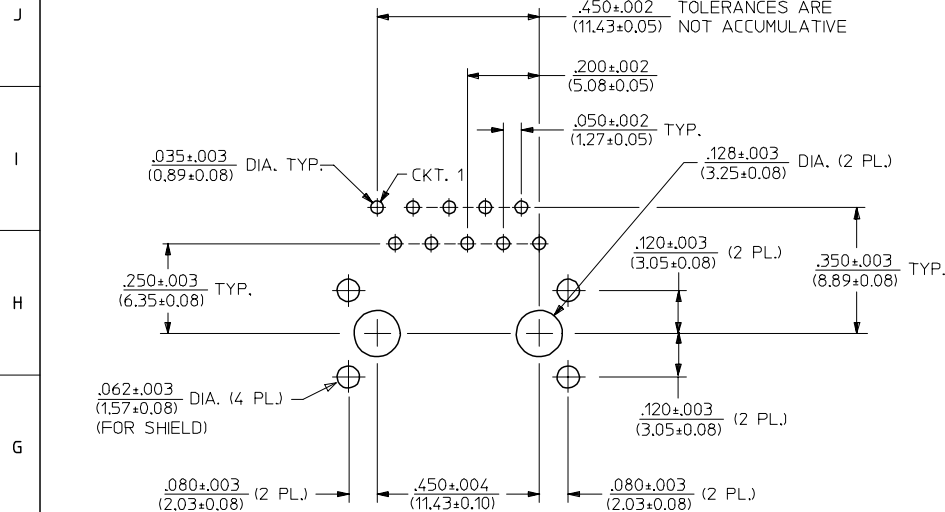


HOUSING SIZE	CIRCUIT SIZE	DIM. B
8	10	.450±.005 (11.43±0.13)
8	8	.350±.005 (8.89±0.13)

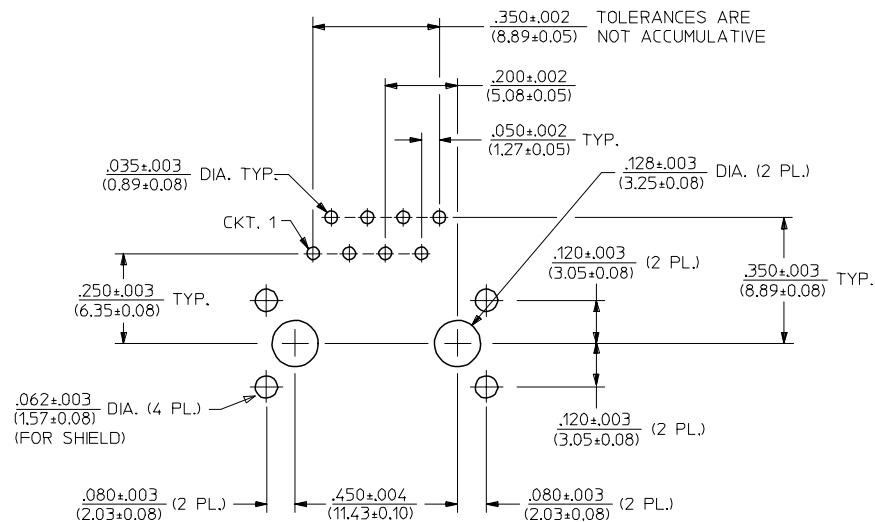


SEE SHEET ONE EC NO: UCP2004-1888 DRAWN: SCHMIDT 2004/03/31 CHKD: SCHMIDT 2004/03/31 APPR: FSMITH 2004/03/31	DESCRIPTION	QUALITY SYMBOLS	 -0  -0	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 4:1	DESIGN UNITS INCH		THIRD ANGLE PROJECTION	REVISE ON CAD ONLY			
						DIMENSION STYLE IN/MM		TITLE ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY					
				4 PLACES	± .010	± .010	DRAWN BY JTR	DATE 1993/03/31	 MOLEX INCORPORATED				
				3 PLACES	± .010	± .010	CHECKED BY JTR	DATE 1993/03/31					
				2 PLACES	± 0.25	± .014	APPROVED BY RAS	DATE 1993/03/31			MATERIAL NO. SEE SHT 6	DOCUMENT NO. SDA-43202	SHEET NO. 3 OF 9
				1 PLACE	± 0.36	± .014	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
				ANGULAR ±1/2°									
				DRAFT WHERE APPLICABLE									
				MUST REMAIN WITHIN DIMENSIONS									

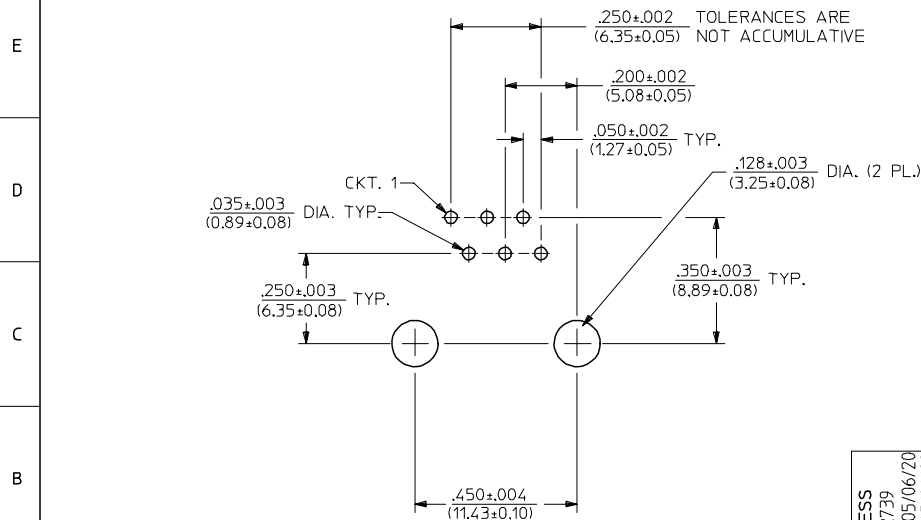
	13	12	11	10	9	8	7	6	5	4	3	2	1			
J	SHIELDED MODULAR JACKS W/O BOTTOM GROUND TABS (SHEET 3)							UNSHIELDED MODULAR JACKS- (SHEET 4)							J	
	ASSEMBLY MATERIAL NUMBER	CONNECTOR SIZE	NUMBER OF CIRCUITS	SIDE/TOP PANEL GROUND TAB OPTION	PCB GROUND TAB OPTION	TERMINAL PLATING OPTION	PACKAGING	HOUSING COLOR	ASSEMBLY MATERIAL NUMBER	CONNECTOR SIZE	NUMBER OF CIRCUITS	TERMINAL PLATING OPTION	KEYING OPTION	PACKAGING OPTION	HOUSING COLOR	
	43202-8800	8	10	E	FRONT POSITION	A	TRAY	BLACK	43202-4101	4	4	A	NO	TRAY	BLACK	
	43202-8801	8	10	F	FRONT POSITION	A	TRAY		43202-4104	4	2	A	NO	TRAY		
I	43202-8802	8	10	G	FRONT POSITION	A	TRAY		43202-6101	6	6	A	NO	TRAY		I
	43202-8803	8	10	H	FRONT POSITION	A	TRAY		43202-6102	6	6	B	NO	TRAY		
	43202-8808	8	10	E	REAR POSITION	A	TRAY		43202-6104	6	4	A	NO	TRAY		
	43202-8809	8	10	F	REAR POSITION	A	TRAY		43202-6105	6	4	B	NO	TRAY		
	43202-8810	8	10	G	REAR POSITION	A	TRAY		43202-6107	6	2	A	NO	TRAY		
	43202-8811	8	10	H	REAR POSITION	A	TRAY		43202-6110	6	6	B	NO	TUBE		
H	43202-8816	8	8	E	FRONT POSITION	A	TRAY		43202-8101	8	10	A	NO	TRAY		H
	43202-8817	8	8	F	FRONT POSITION	A	TRAY		43202-8104	8	8	A	NO	TRAY		
	43202-8818	8	8	G	FRONT POSITION	A	TRAY		43202-8105	8	8	B	NO	TRAY		
	43202-8819	8	8	H	FRONT POSITION	A	TRAY		43202-8113	8	8	A	YES	TRAY		
	43202-8824	8	8	E	REAR POSITION	A	TRAY		43202-8116	8	6	A	NO	TRAY		
	43202-8825	8	8	F	REAR POSITION	A	TRAY		43202-8119	8	4	A	NO	TRAY		
	43202-8826	8	8	G	REAR POSITION	A	TRAY		43202-8122	8	2	A	NO	TRAY		
G	43202-8827	8	8	H	REAR POSITION	A	TRAY		43202-8504	8	8	A	NO	TUBE		G
								43202-8513	8	8	A	YES	TUBE			
F															F	
E															E	
D															D	
C															C	
B															B	
A															A	
OBS COLORED JACKS EC NO: UCP2008-1189 DRWN:JBELL CHKD:LSCHMIDT APPR:FSM1TH 2007/11/30 2008/02/20 2008/03/04 DESCRIPTION REV QUALITY SYMBOLS ▼=0 ▽=0 GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± .014 1 PLACE ± 0.36 ± --- ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS DIMENSION STYLE IN/MM DRAWN BY DATE CHECKED BY DATE APPROVED BY DATE MATERIAL NO. SEE CHART SIZE C SCALE 4:1 DESIGN UNITS INCH THIRD ANGLE PROJECTION ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY MOLEX MOLEX INCORPORATED MATERIAL NO. SDA-43202 SHEET NO. 6 OF 9 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																
	12	11	10	9	8	7	6	5	4	3	2	1				



PC BOARD LAYOUT FOR 8 POSITION HOUSING
(10 CIRCUIT FOOTPRINT SHOWN)
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR 8 POSITION HOUSING
(8 CIRCUIT FOOTPRINT SHOWN)
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR 8 POSITION HOUSING
(6 CIRCUIT FOOTPRINT SHOWN)
(COMPONENT SIDE OF BOARD)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

ADD PCB THICKNESS EC NO: UCP2005-2739 DRWN:LSCHMIDT 2005/06/20 CHKD:ELHAG 2005/06/22 APPR:FSMTH 2005/06/23	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION		REVISE ON CAD ONLY	
				mm	INCH	DIMENSION STYLE IN/MM		TITLE ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY		
			4 PLACES	± ---	± ---	DRAWN BY L.E. LENZ	DATE 1995/03/09			
			3 PLACES	± ---	± .010	CHECKED BY JTR	DATE 1995/03/09			
			2 PLACES	± 0.25	± .014	MATERIAL NO. SEE SHTS 5&6		DOCUMENT NO. SDA-43202		SHEET NO. 9 OF 9
			1 PLACE	± 0.36	± ---					
			ANGULAR ±1/2°		MOLEX MOLEX INCORPORATED					
			DRAFT WHERE APPLICABLE		APPROVED BY RAS		DATE 1995/03/09			
			MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

ADD PCB THICKNESS
EC NO: UCP2005-2739
DRAWN: SCHMIDT 2005/06/20
CHKD: ELHAG 2005/06/22
APPR: FSMITH 2005/06/23
REV L2



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

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